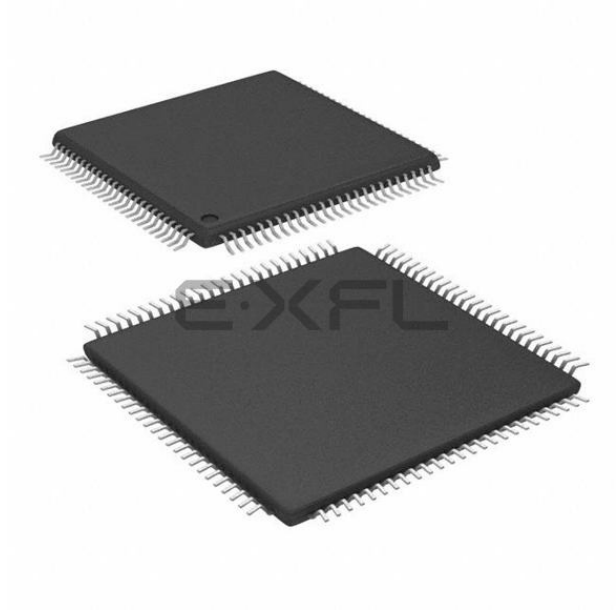
Microchip Technology - DSPIC33FJ128MC510A-I/PT Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, QEI, WDT
Number of I/O	85
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 24x10/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj128mc510a-i-pt

TABLE 7-1: INTERRUPT VECTORS (CONTINUED)

Vector Number	Interrupt Request (IRQ) Number	IVT Address	AIVT Address	Interrupt Source
54	46	0x000070	0x000170	DMA4 – DMA Channel 4
55	47	0x000072	0x000172	T6 – Timer6
56	48	0x000074	0x000174	T7 – Timer7
57	49	0x000076	0x000176	SI2C2 – I2C2 Slave Events
58	50	0x000078	0x000178	MI2C2 – I2C2 Master Events
59	51	0x00007A	0x00017A	T8 – Timer8
60	52	0x00007C	0x00017C	T9 – Timer9
61	53	0x00007E	0x00017E	INT3 – External Interrupt 3
62	54	0x000080	0x000180	INT4 – External Interrupt 4
63	55	0x000082	0x000182	C2RX – ECAN2 Receive Data Ready
64	56	0x000084	0x000184	C2 – ECAN2 Event
65	57	0x000086	0x000186	PWM – PWM Period Match
66	58	0x000088	0x000188	QEI – Position Counter Compare
69	61	0x00008E	0x00018E	DMA5 – DMA Channel 5
70	62	0x000090	0x000190	Reserved
71	63	0x000092	0x000192	$\overline{\text{FLTA}}$ – MCPWM Fault A
72	64	0x000094	0x000194	$\overline{\text{FLTB}}$ – MCPWM Fault B
73	65	0x000096	0x000196	U1E – UART1 Error
74	66	0x000098	0x000198	U2E – UART2 Error
75	67	0x00009A	0x00019A	Reserved
76	68	0x00009C	0x00019C	DMA6 – DMA Channel 6
77	69	0x00009E	0x00019E	DMA7 – DMA Channel 7
78	70	0x0000A0	0x0001A0	C1TX – ECAN1 Transmit Data Request
79	71	0x0000A2	0x0001A2	C2TX – ECAN2 Transmit Data Request
80-125	72-117	0x0000A4-0x0000FE	0x0001A4-0x0001FE	Reserved

TABLE 7-2: TRAP VECTORS

Vector Number	IVT Address	AIVT Address	Trap Source
0	0x000004	0x000104	Reserved
1	0x000006	0x000106	Oscillator Failure
2	0x000008	0x000108	Address Error
3	0x00000A	0x00010A	Stack Error
4	0x00000C	0x00010C	Math Error
5	0x00000E	0x00010E	DMA Error Trap
6	0x000010	0x000110	Reserved
7	0x000012	0x000112	Reserved

REGISTER 7-14: IEC4: INTERRUPT ENABLE CONTROL REGISTER 4

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0
C2TXIE	C1TXIE	DMA7IE	DMA6IE	—	U2EIE	U1EIE	FLTBIE
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as '0'

bit 7 **C2TXIE:** ECAN2 Transmit Data Request Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 6 **C1TXIE:** ECAN1 Transmit Data Request Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 5 **DMA7IE:** DMA Channel 7 Data Transfer Complete Enable Status bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 4 **DMA6IE:** DMA Channel 6 Data Transfer Complete Enable Status bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 3 **Unimplemented:** Read as '0'

bit 2 **U2EIE:** UART2 Error Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 1 **U1EIE:** UART1 Error Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 0 **FLTBIE:** PWM Fault B Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

NOTES:

9.0 OSCILLATOR CONFIGURATION

Note 1: This data sheet summarizes the features of the dsPIC33FJXXXMCX06A/X08A/X10A family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 7. "Oscillator"** (DS70186) in the *"dsPIC33F/PIC24H Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

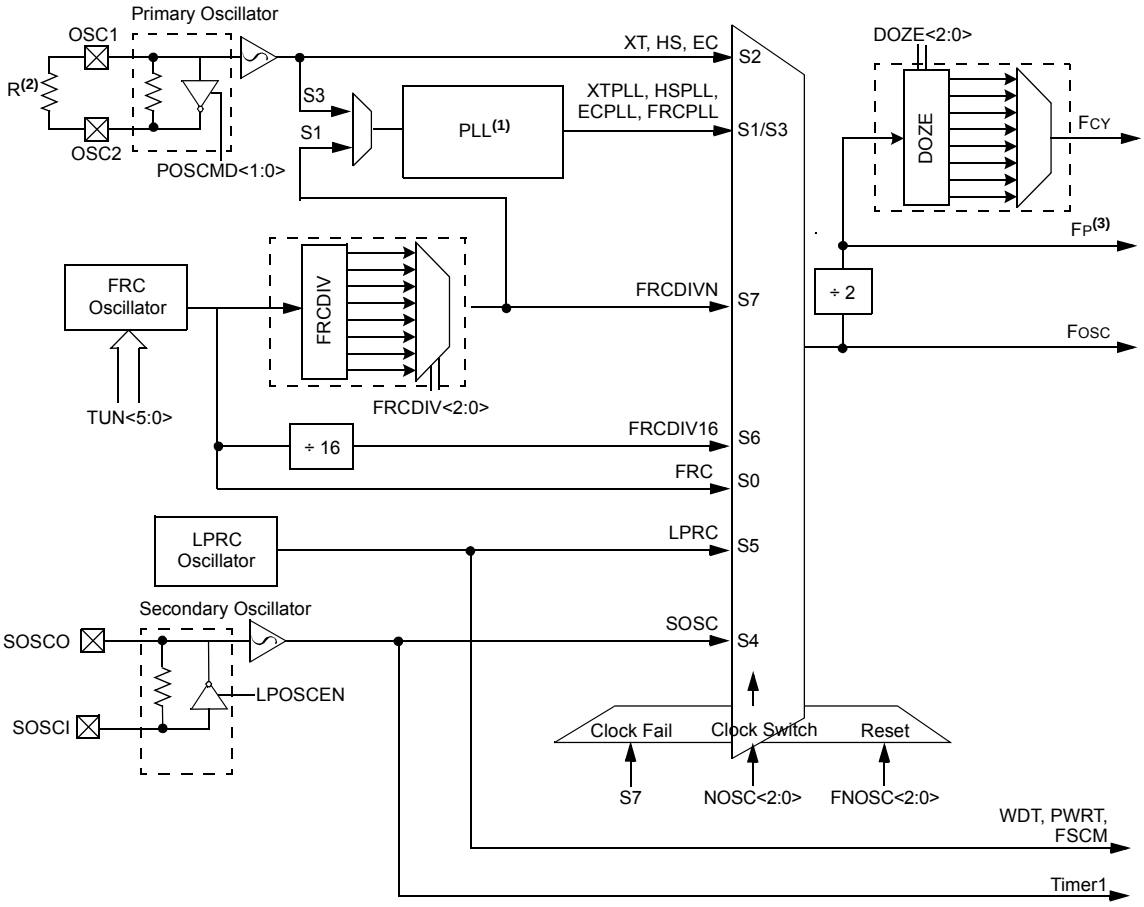
2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33FJXXXMCX06A/X08A/X10A oscillator system provides the following:

- Various external and internal oscillator options as clock sources
- An on-chip PLL to scale the internal operating frequency to the required system clock frequency
- The internal FRC oscillator can also be used with the PLL, thereby allowing full-speed operation without any external clock generation hardware
- Clock switching between various clock sources
- Programmable clock postscaler for system power savings
- A Fail-Safe Clock Monitor (FSCM) that detects clock failure and takes fail-safe measures
- A Clock Control register (OSCCON)
- Nonvolatile Configuration bits for main oscillator selection

A simplified diagram of the oscillator system is shown in Figure 9-1.

FIGURE 9-1: dsPIC33FJXXXMCX06A/X08A/X10A OSCILLATOR SYSTEM DIAGRAM



Note 1: See Figure 9-2 for PLL details.

2: If the Oscillator is used with XT or HS modes, an extended parallel resistor with the value of 1 MΩ must be connected.

3: The term, FP refers to the clock source for all the peripherals, while FCY refers to the clock source for the CPU. Throughout this document FP and FCY are used interchangeably, except in the case of Doze mode. FP and FCY will be different when Doze mode is used in any ratio other than 1:1, which is the default.

13.0 TIMER2/3, TIMER4/5, TIMER6/7 AND TIMER8/9

Note 1: This data sheet summarizes the features of the dsPIC33FJXXXMCX06A/X08A/X10A family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 11. "Timers"** (DS70205) in the *"dsPIC33F/PIC24H Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Timer2/3, Timer4/5, Timer6/7 and Timer8/9 modules are 32-bit timers that can also be configured as four independent 16-bit timers with selectable operating modes.

As a 32-bit timer, Timer2/3, Timer4/5, Timer6/7 and Timer8/9 operate in three modes:

- Two Independent 16-Bit Timers (e.g., Timer2 and Timer3) with all 16-Bit operating modes (except Asynchronous Counter mode)
- Single 32-Bit Timer
- Single 32-Bit Synchronous Counter

They also support the following features:

- Timer Gate Operation
- Selectable Prescaler Settings
- Timer Operation during Idle and Sleep modes
- Interrupt on a 32-Bit Period Register Match
- Time Base for Input Capture and Output Compare Modules (Timer2 and Timer3 only)
- ADC1 Event Trigger (Timer2/3 only)
- ADC2 Event Trigger (Timer4/5 only)

Individually, all eight of the 16-bit timers can function as synchronous timers or counters. They also offer the features listed above, except for the event trigger; this is implemented only with Timer2/3. The operating modes and enabled features are determined by setting the appropriate bit(s) in the T2CON, T3CON, T4CON, T5CON, T6CON, T7CON, T8CON and T9CON registers. T2CON, T4CON, T6CON and T8CON are shown in generic form in Register 13-1. T3CON, T5CON, T7CON and T9CON are shown in Register 13-2.

For 32-bit timer/counter operation, Timer2, Timer4, Timer6 or Timer8 is the least significant word; Timer3, Timer5, Timer7 or Timer9 is the most significant word of the 32-bit timers.

Note: For 32-bit operation, T3CON, T5CON, T7CON and T9CON control bits are ignored. Only T2CON, T4CON, T6CON and T8CON control bits are used for setup and control. Timer2, Timer4, Timer6 and Timer8 clock and gate inputs are utilized for the 32-bit timer modules, but an interrupt is generated with the Timer3, Timer5, Ttimer7 and Timer9 interrupt flags.

To configure Timer2/3, Timer4/5, Timer6/7 or Timer8/9 for 32-bit operation, do the following:

1. Set the corresponding T32 control bit.
2. Select the prescaler ratio for Timer2, Timer4, Timer6 or Timer8 using the TCKPS<1:0> bits.
3. Set the Clock and Gating modes using the corresponding TCS and TGATE bits.
4. Load the timer period value. PR3, PR5, PR7 or PR9 contains the most significant word of the value, while PR2, PR4, PR6 or PR8 contains the least significant word.
5. If interrupts are required, set the interrupt enable bit, T3IE, T5IE, T7IE or T9IE. Use the priority bits, T3IP<2:0>, T5IP<2:0>, T7IP<2:0> or T9IP<2:0>, to set the interrupt priority. While Timer2, Timer4, Timer6 or Timer8 control the timer, the interrupt appears as a Timer3, Timer5, Timer7 or Timer9 interrupt.
6. Set the corresponding TON bit.

The timer value at any point is stored in the register pair, TMR3:TMR2, TMR5:TMR4, TMR7:TMR6 or TMR9:TMR8. TMR3, TMR5, TMR7 or TMR9 always contain the most significant word of the count, while TMR2, TMR4, TMR6 or TMR8 contain the least significant word.

To configure any of the timers for individual 16-bit operation, do the following:

1. Clear the T32 bit corresponding to that timer.
2. Select the timer prescaler ratio using the TCKPS<1:0> bits.
3. Set the Clock and Gating modes using the TCS and TGATE bits.
4. Load the timer period value into the PRx register.
5. If interrupts are required, set the interrupt enable bit, TxIE. Use the priority bits, TxIP<2:0>, to set the interrupt priority.
6. Set the TON bit.

A block diagram for a 32-bit timer pair (Timer4/5) example is shown in Figure 13-1, and a timer (Timer4) operating in 16-bit mode example is shown in Figure 13-2.

Note: Only Timer2 and Timer3 can trigger a DMA data transfer.

REGISTER 17-1: QEIxCON: QEIx CONTROL REGISTER (CONTINUED)

bit 4-3 **TQCKPS<1:0>:** Timer Input Clock Prescale Select bits
11 = 1:256 prescale value
10 = 1:64 prescale value
01 = 1:8 prescale value
00 = 1:1 prescale value
(Prescaler utilized for 16-Bit Timer mode only.)

bit 2 **POSRES:** Position Counter Reset Enable bit
1 = Index pulse resets position counter
0 = Index pulse does not reset position counter
(Bit only applies when QEIM<2:0> = 100 or 110.)

bit 1 **TQCS:** Timer Clock Source Select bit
1 = External clock from QEA pin (on the rising edge)
0 = Internal clock (TCY)

bit 0 **UPDN_SRC:** Position Counter Direction Selection Control bit(1)
1 = QEB pin state defines position counter direction
0 = Control/status bit, UPDN (QEICON<11>), defines Position Counter (POSxCNT) direction

Note 1: When configured for QEI mode, the control bit is a ‘don’t care’.

REGISTER 18-3: SPIxCON2: SPIx CONTROL REGISTER 2

R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0	U-0
FRMEN	SPIFSD	FRMPOL	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	U-0
—	—	—	—	—	—	FRMDLY	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **FRMEN:** Framed SPIx Support bit
1 = Framed SPIx support enabled ($\overline{SSx}$ pin used as frame Sync pulse input/output)
0 = Framed SPIx support disabled

bit 14 **SPIFSD:** Frame Sync Pulse Direction Control bit
1 = Frame Sync pulse input (slave)
0 = Frame Sync pulse output (master)

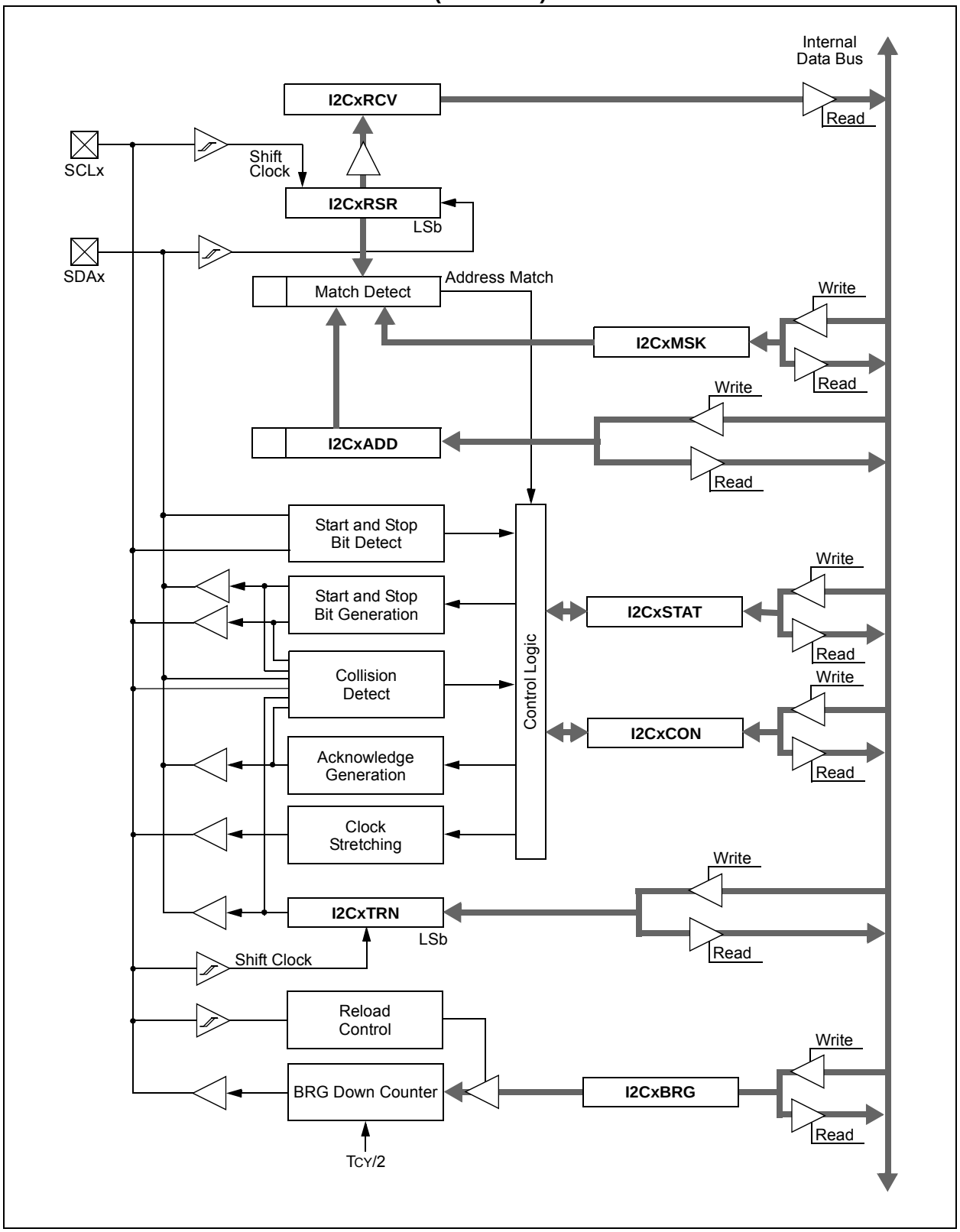
bit 13 **FRMPOL:** Frame Sync Pulse Polarity bit
1 = Frame Sync pulse is active-high
0 = Frame Sync pulse is active-low

bit 12-2 **Unimplemented:** Read as '0'

bit 1 **FRMDLY:** Frame Sync Pulse Edge Select bit
1 = Frame Sync pulse coincides with first bit clock
0 = Frame Sync pulse precedes first bit clock

bit 0 **Unimplemented:** This bit must not be set to '1' by the user application.

FIGURE 19-1: I²C™ BLOCK DIAGRAM (x = 1 OR 2)



22.0 10-BIT/12-BIT ANALOG-TO-DIGITAL CONVERTER (ADC)

Note 1: This data sheet summarizes the features of the dsPIC33FJXXXMCX06A/X08A/X10A family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 16. "Analog-to-Digital Converter (ADC)"** (DS70183) in the *"dsPIC33F/PIC24H Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33FJXXXMCX06A/X08A/X10A devices have up to 32 ADC input channels. These devices also have up to 2 ADC modules (ADCx, where 'x' = 1 or 2), each with its own set of Special Function Registers.

The AD12B bit (ADxCON1<10>) allows each of the ADC modules to be configured by the user as either a 10-bit, 4-sample/hold ADC (default configuration) or a 12-bit, 1-sample/hold ADC.

Note: The ADC module needs to be disabled before modifying the AD12B bit.

22.1 Key Features

The 10-bit ADC configuration has the following key features:

- Successive Approximation (SAR) conversion
- Conversion speeds of up to 1.1 Msps
- Up to 32 analog input pins
- External voltage reference input pins
- Simultaneous sampling of up to four analog input pins
- Automatic Channel Scan mode
- Selectable conversion trigger source
- Selectable Buffer Fill modes
- Four result alignment options (signed/unsigned, fractional/integer)
- Operation during CPU Sleep and Idle modes

The 12-bit ADC configuration supports all the above features, except:

- In the 12-bit configuration, conversion speeds of up to 500 ksps are supported.
- There is only 1 sample/hold amplifier in the 12-bit configuration, so simultaneous sampling of multiple channels is not supported.

Depending on the particular device pinout, the ADC can have up to 32 analog input pins, designated AN0 through AN31. In addition, there are two analog input pins for external voltage reference connections. These voltage reference inputs may be shared with other analog input pins. The actual number of analog input pins and external voltage reference input configuration will depend on the specific device.

A block diagram of the ADC is shown in Figure 22-1.

22.2 ADC Initialization

The following configuration steps should be performed.

1. Configure the ADC module:
   a) Select port pins as analog inputs (ADxPCFGH<15:0> or ADxPCFGL<15:0>)
   b) Select voltage reference source to match expected range on analog inputs (ADxCON2<15:13>)
   c) Select the analog conversion clock to match desired data rate with processor clock (ADxCON3<7:0>)
   d) Determine how many S/H channels will be used (ADxCON2<9:8> and ADxPCFGH<15:0> or ADxPCFGL<15:0>)
   e) Select the appropriate sample/conversion sequence (ADxCON1<7:5> and ADxCON3<12:8>)
   f) Select how conversion results are presented in the buffer (ADxCON1<9:8>)
   g) Turn on ADC module (ADxCON1<15>)
2. Configure ADC interrupt (if required):
   a) Clear the ADxIF bit
   b) Select ADC interrupt priority

22.3 ADC and DMA

If more than one conversion result needs to be buffered before triggering an interrupt, DMA data transfers can be used. Both ADC1 and ADC2 can trigger a DMA data transfer. If ADC1 or ADC2 is selected as the DMA IRQ source, a DMA transfer occurs when the AD1IF or AD2IF bit gets set as a result of an ADC1 or ADC2 sample conversion sequence.

The SMPI<3:0> bits (ADxCON2<5:2>) are used to select how often the DMA RAM Buffer Pointer is incremented.

The ADDMABM bit (ADxCON1<12>) determines how the conversion results are filled in the DMA RAM buffer area being used for ADC. If this bit is set, DMA buffers are written in the order of conversion. The module will provide an address to the DMA channel that is the same as the address used for the non-DMA stand-alone buffer. If the ADDMABM bit is cleared, then DMA buffers are written in Scatter/Gather mode. The module will provide a scatter/gather address to the DMA channel, based on the index of the analog input and the size of the DMA buffer.

REGISTER 22-1: ADxCON1: ADCx CONTROL REGISTER 1 (where x = 1 or 2)

R/W-0	U-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0
ADON	—	ADSIDL	ADDMABM	—	AD12B	FORM<1:0>	
bit 15							bit 8

R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0, HC,HS	R/C-0, HC, HS
SSRC<2:0>			—	SIMSAM	ASAM	SAMP	DONE
bit 7							bit 0

Legend:	HC = Hardware Clearable bit	HS = Hardware Settable bit	C= Clearable bit
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ADON:** ADC Operating Mode bit
1 = ADC module is operating
0 = ADC is off

bit 14 **Unimplemented:** Read as '0'

bit 13 **ADSIDL:** Stop in Idle Mode bit
1 = Discontinue module operation when device enters Idle mode
0 = Continue module operation in Idle mode

bit 12 **ADDMABM:** DMA Buffer Build Mode bit
1 = DMA buffers are written in the order of conversion. The module will provide an address to the DMA channel that is the same as the address used for the non-DMA stand-alone buffer
0 = DMA buffers are written in Scatter/Gather mode. The module will provide a scatter/gather address to the DMA channel, based on the index of the analog input and the size of the DMA buffer

bit 11 **Unimplemented:** Read as '0'

bit 10 **AD12B:** 10-Bit or 12-Bit Operation Mode bit
1 = 12-bit, 1-channel ADC operation
0 = 10-bit, 4-channel ADC operation

bit 9-8 **FORM<1:0>:** Data Output Format bits
For 10-Bit Operation:
11 = Signed fractional (DOUT = sddd dddd dd00 0000, where s = .NOT.d<9>)
10 = Fractional (DOUT = dddd dddd dd00 0000)
01 = Signed integer (DOUT = ssss sssd dddd dddd, where s = .NOT.d<9>)
00 = Integer (DOUT = 0000 00dd dddd dddd)
For 12-Bit Operation:
11 = Signed fractional (DOUT = sddd dddd dddd 0000, where s = .NOT.d<11>)
10 = Fractional (DOUT = dddd dddd dddd 0000)
01 = Signed Integer (DOUT = ssss sddd dddd dddd, where s = .NOT.d<11>)
00 = Integer (DOUT = 0000 dddd dddd dddd)

bit 7-5 **SSRC<2:0>:** Sample Clock Source Select bits
111 = Internal counter ends sampling and starts conversion (auto-convert)
110 = Reserved
101 = Reserved
100 = GP timer (Timer5 for ADC1, Timer3 for ADC2) compare ends sampling and starts conversion
011 = MPWM interval ends sampling and starts conversion
010 = GP timer (Timer3 for ADC1, Timer5 for ADC2) compare ends sampling and starts conversion
001 = Active transition on INT0 pin ends sampling and starts conversion
000 = Clearing sample bit ends sampling and starts conversion

bit 4 **Unimplemented:** Read as '0'

REGISTER 22-2: ADxCON2: ADCx CONTROL REGISTER 2 (CONTINUED) (where x = 1 or 2)

bit 0 **ALTS:** Alternate Input Sample Mode Select bit

1 = Uses channel input selects for Sample A on first sample and Sample B on next sample

0 = Always uses channel input selects for Sample A

TABLE 24-1: SYMBOLS USED IN OPCODE DESCRIPTIONS (CONTINUED)

Field	Description
Wm*Wm	Multiplicand and Multiplier working register pair for Square instructions ∈ {W4 * W4,W5 * W5,W6 * W6,W7 * W7}
Wm*Wn	Multiplicand and Multiplier working register pair for DSP instructions ∈ {W4 * W5,W4 * W6,W4 * W7,W5 * W6,W5 * W7,W6 * W7}
Wn	One of 16 working registers ∈ {W0..W15}
Wnd	One of 16 destination working registers ∈ {W0...W15}
Wns	One of 16 source working registers ∈ {W0...W15}
WREG	W0 (working register used in file register instructions)
Ws	Source W register ∈ {Ws, [Ws], [Ws++], [Ws--], [++Ws], [--Ws]}
Wso	Source W register ∈ {Wns, [Wns], [Wns++], [Wns--], [++Wns], [--Wns], [Wns+Wb]}
Wx	X Data Space Prefetch Address register for DSP instructions ∈ {[W8]+ = 6, [W8]+ = 4, [W8]+ = 2, [W8], [W8]- = 6, [W8]- = 4, [W8]- = 2, [W9]+ = 6, [W9]+ = 4, [W9]+ = 2, [W9], [W9]- = 6, [W9]- = 4, [W9]- = 2, [W9 + W12], none}
Wxd	X Data Space Prefetch Destination register for DSP instructions ∈ {W4...W7}
Wy	Y Data Space Prefetch Address register for DSP instructions ∈ {[W10]+ = 6, [W10]+ = 4, [W10]+ = 2, [W10], [W10]- = 6, [W10]- = 4, [W10]- = 2, [W11]+ = 6, [W11]+ = 4, [W11]+ = 2, [W11], [W11]- = 6, [W11]- = 4, [W11]- = 2, [W11 + W12], none}
Wyd	Y Data Space Prefetch Destination register for DSP instructions ∈ {W4...W7}

TABLE 26-4: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
Operating Voltage							
DC10	**Supply Voltage**						
	VDD	—	3.0	—	3.6	V	—
DC12	VDR	**RAM Data Retention Voltage(2)**	1.8	—	—	V	—
DC16	VPOR	**VDD Start Voltage** to Ensure Internal Power-on Reset Signal	—	—	VSS	V	—
DC17	SVDD	**VDD Rise Rate** to Ensure Internal Power-on Reset Signal	0.03	—	—	V/ms	0-3.0V in 0.1s

Note 1: Data in “Typ” column is at 3.3V, 25°C unless otherwise stated.

2: This is the limit to which VDD can be lowered without losing RAM data.

FIGURE 26-2: EXTERNAL CLOCK TIMING

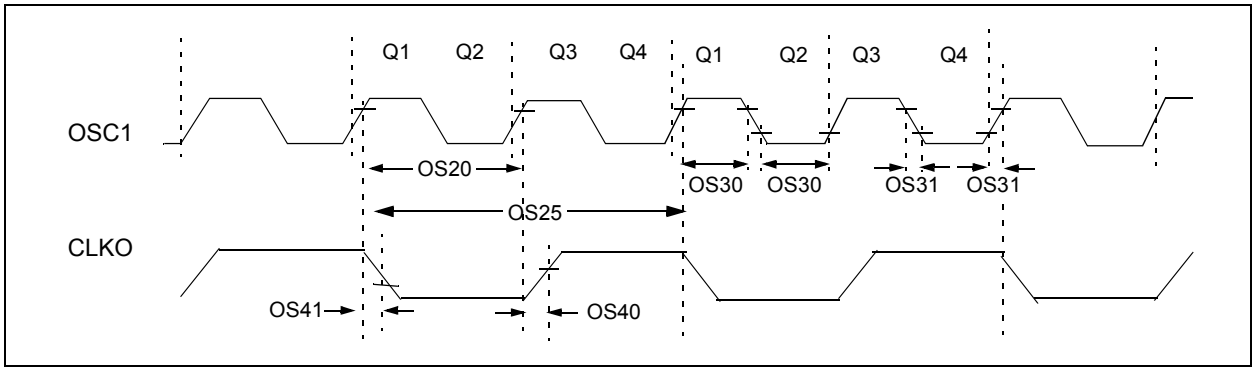


TABLE 26-16: EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symb**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
OS10	FIN	External CLKI Frequency (External clocks allowed only in EC and ECPLL modes)	DC	—	40	MHz	EC
		Oscillator Crystal Frequency	3.5 10 —	— — —	10 40 33	MHz MHz kHz	XT HS SOSC
OS20	TOSC	TOSC = 1/FOSC	12.5	—	DC	ns	—
OS25	TCY	Instruction Cycle Time(2)	25	—	DC	ns	—
OS30	TosL, TosH	External Clock in (OSC1) High or Low Time	0.375 x TOSC	—	0.625 x TOSC	ns	EC
OS31	TosR, TosF	External Clock in (OSC1) Rise or Fall Time	—	—	20	ns	EC
OS40	TckR	CLKO Rise Time(3)	—	5.2	—	ns	—
OS41	TckF	CLKO Fall Time(3)	—	5.2	—	ns	—
OS42	GM	External Oscillator Transconductance(4)	14	16	18	mA/V	VDD = 3.3V, TA = +25°C

Note 1: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

2: Instruction cycle period (TCY) equals two times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKI pin. When an external clock input is used, the "max." cycle time limit is "DC" (no clock) for all devices.

3: Measurements are taken in EC mode. The CLKO signal is measured on the OSC2 pin.

4: Data for this parameter is preliminary. This parameter is characterized, but not tested in manufacturing.

TABLE 26-43: ADC MODULE SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ**	**Max.**	**Units**	**Conditions**
Device Supply							
AD01	AVDD	Module VDD Supply	Greater of VDD – 0.3 or 3.0	—	Lesser of VDD + 0.3 or 3.6	V	—
AD02	AVSS	Module VSS Supply	VSS – 0.3	—	VSS + 0.3	V	—
Reference Inputs							
AD05	VREFH	Reference Voltage High	AVSS + 2.5	—	AVDD	V	—
AD05a			3.0	—	3.6	V	VREFH = AVDD VREFL = AVSS = 0
AD06	VREFL	Reference Voltage Low	AVSS	—	AVDD – 2.5	V	—
AD06a			0	—	0	V	VREFH = AVDD VREFL = AVSS = 0
AD07	VREF	Absolute Reference Voltage	2.5	—	3.6	V	VREF = VREFH - VREFL
AD08	IREF	Current Drain	—	—	10	μA	ADC off
AD08a	IAD	Operating Current	— —	7.0 2.7	9.0 3.2	mA mA	10-bit ADC mode, see **Note 1** 12-bit ADC mode, see **Note 1**
Analog Input							
AD12	VINH	Input Voltage Range VINH	VINL	—	VREFH	V	This voltage reflects Sample and Hold Channels 0, 1, 2 and 3 (CH0-CH3), positive input
AD13	VINL	Input Voltage Range VINL	VREFL	—	AVSS + 1V	V	This voltage reflects Sample and Hold Channels 0, 1, 2 and 3 (CH0-CH3), negative input
AD17	RIN	Recommended Impedance of Analog Voltage Source	— —	— —	200 200	Ω Ω	10-bit ADC 12-bit ADC

Note 1: These parameters are not characterized or tested in manufacturing.

TABLE 26-45: ADC MODULE SPECIFICATIONS (10-BIT MODE)(1)

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ**	**Max.**	**Units**	**Conditions**
ADC Accuracy (10-Bit Mode) – Measurements with External VREF+/VREF-							
AD20c	Nr	Resolution	10 data bits			bits	—
AD21c	INL	Integral Nonlinearity	-1.5	—	+1.5	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
AD22c	DNL	Differential Nonlinearity	>-1	—	<1	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
AD23c	GERR	Gain Error	—	3	6	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
AD24c	EOFF	Offset Error	—	2	5	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
AD25c	—	Monotonicity	—	—	—	—	Guaranteed
ADC Accuracy (10-Bit Mode) – Measurements with Internal VREF+/VREF-							
AD20d	Nr	Resolution	10 data bits			bits	—
AD21d	INL	Integral Nonlinearity	-1	—	+1	LSb	VINL = AVSS = 0V, AVDD = 3.6V
AD22d	DNL	Differential Nonlinearity	>-1	—	<1	LSb	VINL = AVSS = 0V, AVDD = 3.6V
AD23d	GERR	Gain Error	—	7	15	LSb	VINL = AVSS = 0V, AVDD = 3.6V
AD24d	EOFF	Offset Error	—	3	7	LSb	VINL = AVSS = 0V, AVDD = 3.6V
AD25d	—	Monotonicity	—	—	—	—	Guaranteed
Dynamic Performance (10-Bit Mode)							
AD30b	THD	Total Harmonic Distortion	—	—	-64	dB	—
AD31b	SINAD	Signal to Noise and Distortion	57	58.5	—	dB	—
AD32b	SFDR	Spurious Free Dynamic Range	72	—	—	dB	—
AD33b	FNYQ	Input Signal Bandwidth	—	—	550	kHz	—
AD34b	ENOB	Effective Number of Bits	9.16	9.4	—	bits	—

Note 1: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.

27.0 HIGH TEMPERATURE ELECTRICAL CHARACTERISTICS

This section provides an overview of dsPIC33FJXXXMCX06A/X08A/X10A electrical characteristics for devices operating in an ambient temperature range of -40°C to +150°C.

The specifications between -40°C to +150°C are identical to those shown in **Section 26.0 "Electrical Characteristics"** for operation between -40°C to +125°C, with the exception of the parameters listed in this section.

Parameters in this section begin with an H, which denotes High temperature. For example, parameter DC10 in **Section 26.0 "Electrical Characteristics"** is the Industrial and Extended temperature equivalent of HDC10.

Absolute maximum ratings for the dsPIC33FJXXXMCX06A/X08A/X10A high temperature devices are listed below. Exposure to these maximum rating conditions for extended periods can affect device reliability. Functional operation of the device at these or any other conditions above the parameters indicated in the operation listings of this specification is not implied.

Absolute Maximum Ratings(1)

Ambient temperature under bias(4) ..... -40°C to +150°C
Storage temperature ..... -65°C to +160°C
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +4.0V
Voltage on any pin that is not 5V tolerant with respect to V_{SS}(5) ..... -0.3V to (V_{DD} + 0.3V)
Voltage on any 5V tolerant pin with respect to V_{SS} when V_{DD} < 3.0V(5) ..... -0.3V to (V_{DD} + 0.3V)
Voltage on any 5V tolerant pin with respect to V_{SS} when $V_{DD} \geq$ 3.0V(5) ..... -0.3V to 5.6V
Voltage on V_{CAP} with respect to V_{SS} ..... 2.25V to 2.75V
Maximum current out of V_{SS} pin ..... 60 mA
Maximum current into V_{DD} pin(2) ..... 60 mA
Maximum junction temperature ..... +155°C
Maximum current sourced/sunk by any 2x I/O pin(3) ..... 2 mA
Maximum current sourced/sunk by any 4x I/O pin(3) ..... 4 mA
Maximum current sourced/sunk by any 8x I/O pin(3) ..... 8 mA
Maximum current sunk by all ports combined ..... 10 mA
Maximum current sourced by all ports combined(2) ..... 10 mA

Note 1: Stresses above those listed under "Absolute Maximum Ratings" can cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods can affect device reliability.

2: Maximum allowable current is a function of device maximum power dissipation (see Table 27-2).

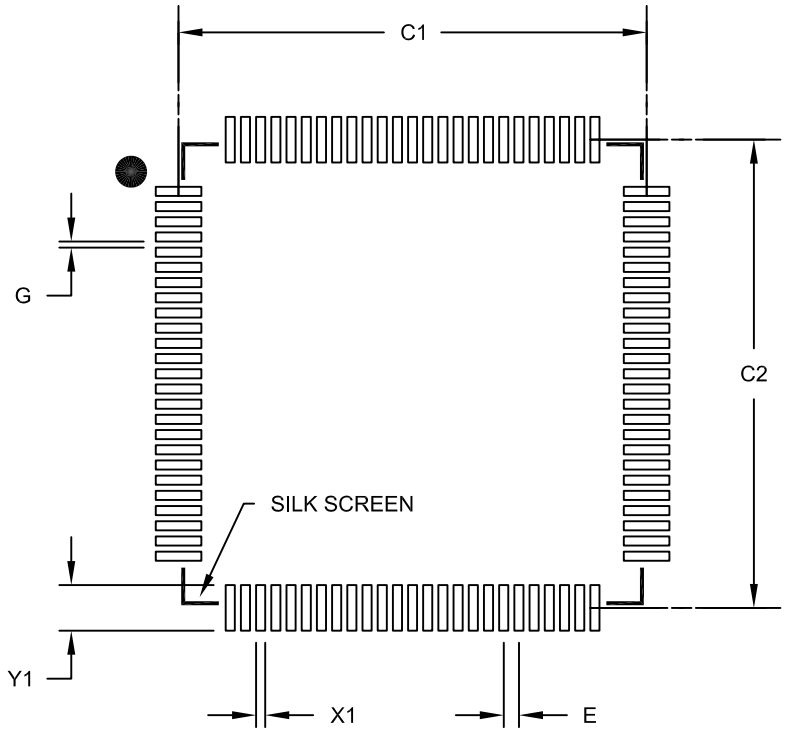
3: Unlike devices at 125°C and below, the specifications in this section also apply to the CLKOUT, V_{REF+}, V_{REF-}, SCLx, SDAx, PGECx, and PGEDx pins.

4: AEC-Q100 reliability testing for devices intended to operate at 150°C is 1,000 hours. Any design in which the total operating time from 125°C to 150°C will be greater than 1,000 hours is not warranted without prior written approval from Microchip Technology Inc.

5: Refer to the **"Pin Diagrams"** section for 5V tolerant pins.

100-Lead Plastic Thin Quad Flatpack (PF) - 14x14x1 mm Body 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Contact Pad Spacing	C1		15.40	
Contact Pad Spacing	C2		15.40	
Contact Pad Width (X100)	X1			0.30
Contact Pad Length (X100)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2110B

Revision D (June 2012)

This revision includes typographical and formatting changes throughout the data sheet text.

All other major changes are referenced by their respective section in the following table.

TABLE B-3: MAJOR SECTION UPDATES

Section Name	Update Description
Section 2.0 "Guidelines for Getting Started with 16-bit Digital Signal Controllers"	Updated the Recommended Minimum Connection (see Figure 2-1).
Section 9.0 "Oscillator Configuration"	Updated the COSC<2:0> and NOSC<2:0> bit value definitions for '001' (see Register 9-1).
Section 22.0 "10-bit/12-bit Analog-to-Digital Converter (ADC)"	Updated the Analog-to-Digital Conversion Clock Period Block Diagram (see Figure 22-2).
Section 23.0 "Special Features"	Added Note 3 to the On-chip Voltage Regulator Connections (see Figure 23-1).
Section 26.0 "Electrical Characteristics"	Updated **"Absolute Maximum Ratings"**. Updated Operating MIPS vs. Voltage (see Table 26-1). Removed parameter DC18 from the DC Temperature and Voltage Specifications (see Table 26-4). Updated the notes in the following tables: • Table 26-5 • Table 26-6 • Table 26-7 • Table 26-8 Updated the I/O Pin Output Specifications (see Table 26-10). Updated the Conditions for parameter BO10 (see Table 26-11). Updated the Conditions for parameters D136b, D137b and D138b (T_A = 150ºC) (see Table 26-12).
Section 27.0 "High Temperature Electrical Characteristics"	Updated **"Absolute Maximum Ratings(1)"**. Updated the I/O Pin Output Specifications (see Table 27-6). Removed Table 26-7: DC Characteristics: Program Memory.

NOTES: